

Title (en)

METHOD OF MAKING A NICKEL-COATED COPPER SUBSTRATE AND THIN FILM COMPOSITE CONTAINING THE SAME

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES MIT NICKEL ÜBERZOGENEN KUPFERSUBSTRATES UND DIESES ENTHALTENDES DÜNNSCHICHTVERBUNDATERIAL

Title (fr)

PROCEDE DE FABRICATION D'UN SUBSTRAT EN CUIVRE RECOUVERT DE NICKEL ET COMPOSITE DE FILM MINCE CONTENANT LE MEME

Publication

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Application

EP 01945555 A 20010628

Priority

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Abstract (en)

[origin: WO03002782A1] The invention relates to a process of preparing a copper/nickel substrate by annealing nickel-coated copper. After the nickel deposition step, a dielectric, such as lead zirconate titanate (PZT), may be deposited onto the substrate by methods known in the art such as sol-gel or vacuum deposition. This invention further relates to thin film composites. These composites comprise a pre-annealed nickel-coated copper substrate and a dielectric such as PZT.

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